The International Conference on Communications (ICC) is one of the two flagship conferences of the IEEE Communications Society, together with IEEE GLOBECOM. Each year the IEEE ICC conference attracts about 3,000 submitted scientific papers, a technical program committee involving about 1,500 experts provides more than 10,000 reviews, and the conference is finally attended by 1,500 – 2,000 professionals from all around the world. IEEE ICC is therefore one of the most significant scientific events of the networking and communications community, a must-attend forum for both industrials and academics working in this area.

**Conference Program**

The IEEE ICC conference is a five-day event, three days being dedicated to the technical symposia and two days to tutorials and workshops. The program of the technical symposia includes oral and poster presentations of about 1,000 scientific papers, grouped into 12 thematic tracks, and 18 to 20 parallel sessions. In addition, the conference program includes workshops, tutorials, keynote talks from industrial leaders and renowned academics, panel discussions and a large exhibition.

**Expected Participation**

We expect about 1,500 participants from all over the world.

About 30 exhibition booths give enough space for presentations and demonstrations of recent advances in research and development.

In 2013 the IEEE ICC conference will be held for the first time in Eastern Europe.

More information: www.ieee-icc.org/2013
Patronage means leadership

◊ Your patronage validates the leadership of your organization in the industry and positions your company to gain maximum exposure with IEEE ICC 2013 attendees.

◊ Use this business-building event to share your company’s products and services with important decision makers in the industry.

◊ Patron status maximizes your company’s visibility and enhances your company’s reputation.

◊ IEEE ICC 2013 gives you access to thousands of people that you want to reach and influence.

◊ Your company will be prominently featured as an IEEE ICC 2013 patron.

◊ Showcase your brand to the most influential engineering audience in communications technology.

Why Become a Patron?

The IEEE ICC is the global, world-class event to present the most recent results from research, development and standardization.

The IEEE ICC brings together industry leaders and scientists from around the globe to debate, discuss and learn about the technologies, business opportunities and new applications.

Patrons enjoy extraordinary visibility with the powerful audience at the conference. There is no competition for time between conference sessions and networking receptions. The character of the event as a place where important ideas are exchanged is evident and continually reinforced throughout the event.

The IEEE ICC attracts the “Who’s Who” in communications, i.e., leading customers, operators, vendors, researchers, investors and press. Attendees mingle in a relaxed environment, and discuss the future of communications with those who are shaping it.

Patrons gain access to research executives and directors of some of the world’s leading R&D organizations and project representatives. The event’s attendees are responsible for setting R&D and product development goals and have a considerable budget responsibility.

The IEEE ICC has a long track record and an increasingly powerful, loyal audience. Since 1965 it has a reputation as “major communications event”.

We would welcome your own ideas for discussion, and would be glad to assist with any enquiries you may have. The wide range of opportunities available means that you can choose a package that fits your particular marketing strategy. Some opportunities are negotiable.

Previous Patrons

IEEE ICC’12 Canada: Telus, Alcatel-Lucent, Huawei, Algonquin College, Carlton University, Ciena, CISCO, Ericsson, IBM, Nokia Siemens Networks Exfo, Fujitsu, IET, Juniper Networks, NetCracker, Oracle, RIM, Sigma, Subex


IEEE ICC’09 Germany: Qualcomm, CISCO, Deutsche Telekom, Dresden, NEC, Nokia Siemens Networks, Vodafone DLR, Ericsson, Saxony State Ministry for Economic Affairs and Labour, Signation, ST Ericsson, TU Dresden, Tektronix, UMTS Forum

IEEE ICC’08 China: China Telecom, China Mobile, CN, China Unicom, Huawei, ZTE, Ericsson Broadcom, France Telecom, Fujitsu, Nokia, Panasonic

IEEE ICC’07 Scotland: Scottish Development International, Scottish Enterprise, Picsel Technologies, Scottich Executive, Vodafone, Alcatel-Lucent, Nokia Siemens Networks, Qualcomm

IEEE ICC’06 Turkey: Turkcell, Alcatel, Turk Telekom, Siemens, Tübitak, CISCO, eKom, Ericsson, Havelsan, HP, Karel, Nokia, Telently
### Patronage Packages

#### Overview

<table>
<thead>
<tr>
<th>Feature</th>
<th>Platinum</th>
<th>Gold</th>
<th>Silver</th>
<th>Bronze</th>
<th>Associate</th>
</tr>
</thead>
<tbody>
<tr>
<td>Banner or roll-up with your company name and patronage level in the foyer area of the conference venue</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>X</td>
</tr>
<tr>
<td>Your company name and patronage level listed on a display panel in the foyer area of the venue</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>X X</td>
</tr>
<tr>
<td>Company-flag / roll-up in front of the venue</td>
<td></td>
<td>6</td>
<td>3</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Keynote speech during conference (subject to approval by OC/TCP)</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>X</td>
</tr>
<tr>
<td>Acknowledgement by the chairman during Welcome Reception, Opening and Banquet</td>
<td>Welcome, Opening, Banquet</td>
<td>Opening, Banquet</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Keynote address</td>
<td>X</td>
<td></td>
<td></td>
<td></td>
<td>X</td>
</tr>
<tr>
<td>Full conference registrations and access to social events (#)</td>
<td>5</td>
<td>3</td>
<td>2</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Invitations to the exclusive „VIP” welcome reception (#)</td>
<td>3</td>
<td>2</td>
<td>1</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Advertisement in the Final Program (Full / half page)</td>
<td>Full page</td>
<td>Full</td>
<td>Half</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Patron’s material added to conference bag</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Complimentary 2m x 3m exhibition booths</td>
<td>Double size</td>
<td>Single size</td>
<td>Single size</td>
<td>Single size</td>
<td></td>
</tr>
<tr>
<td>Listed on IEEE ICC 2013 conference website…</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>X</td>
</tr>
<tr>
<td>- Your company logo</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>X</td>
</tr>
<tr>
<td>- Paragraph about the company/organization (up to #)</td>
<td>375 words</td>
<td>375</td>
<td>250</td>
<td>125</td>
<td>125</td>
</tr>
<tr>
<td>- Company/organization website URL</td>
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<td>X</td>
<td>X</td>
<td>X</td>
<td>X</td>
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<tr>
<td>Available up to</td>
<td>2</td>
<td>5</td>
<td>8</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

#### Patronage Packages

- **Platinum Patron Packages** $ 40,000
- **Gold Patron Packages** $ 20,000
- **Silver Patron Packages** $ 10,000
- **Bronze Patron Packages** $ 6,000
- **Associate Patron Packages** $ 3,500

#### Special Patronage Packages

Please note that all patronage packages can be customized to suit your company’s preferences. In addition, there is a possibility to build patronage packages to include visibility at special program items like Conference Banquet, Awards Luncheon, Welcome Reception, Luncheons, Coffee Breaks, etc., or through conference collateral like Final Program, Conference Bag, Proceedings and Lanyard. Please contact the organizers for more details.


#### Advertisement in the Final Program

The Final Program will contain all of the essential conference information and will be used as a reference guidebook well after the conference is over. Please note that the Full Conference Papers will be included in the Proceedings that the attendees will receive on USB sticks (no printed version).

- Full page advertisement: $ 3,000
- Half-page advertisement: $ 2,000
Exhibition

The IEEE ICC 2013 will take place at three luxurious 5-star hotels, Intercontinental, Marriott and Sofitel, situated one next to the other.

To broaden the diversity of the conference, the IEEE ICC 2013 provides an integrated exhibition area close to technical sessions, coffee areas and poster areas to ensure frequent attendance. This is an excellent chance to present your company and its recent results, as well as to get in touch with other young and senior scientists from industry and academia. In addition, to provide you the best possible benefit, the exhibition areas will be grouped by topic.

The following exhibition booth dimensions are offered:
- 2m x 3m $3,000
- 2m x 6m $5,000
- 2m x 9m $7,000

Each booth is equipped with a power supply. Any furniture or additional equipment is subject to additional fees.

The actual placement of the exhibition booth is determined by the conference organizers.

We expect about 1500 participants from all over the world.

About 30 exhibition booths give enough space for presentations and demonstrations of recent advances in research and development.

Exhibition Chair:
Nigel Jefferies
Huawei Technologies
e-mail: nigel.jefferies@huawei.com

About Hungary

Hungary is situated in the very heart of Europe. With a history going back more than 1100 years, it has joined the European Union in May 2004. The country has a size of ~36,000 sq mi (93,000 km2), which makes it similar in size to Indiana, South Korea or Portugal. It has a population of about 10 million inhabitants.

Hungary is rich in history and creativity – it’s the birthplace of world-famous inventors, scientists, mathematicians, explorers, composers and sports stars. This is a place of variety, colour and passion.

About Budapest

Budapest is the capital city of Hungary, and has a population of 1.7 million inhabitants. It is one of Europe’s most beautiful cities, being often called “the pearl of the Danube”.

The twin cities of Buda and Pest, divided by the Danube, united in 1873 to form the city of Budapest. Its architecture is characterized by homogenous parts of different building periods, such as vestiges of the Roman occupation, the prestigious Castle District preserved in Romanesque and Gothic style, the rigor of the Habsburg Citadel, the eclecticism of the turn-of-the-century buildings boasting the richness of the new citizens. It’s truly a city where East meets West, and where people are historically familiar with both cultures, while their own culture and language remains unique. Visitors from all over the World feel at home here.

Conference Venue

The IEEE ICC 2013 will take place at three luxurious 5-star hotels (Intercontinental, Marriott and Sofitel), situated one next to the other, in the very heart of the city, on the banks of the river Danube. The hotels offer a magnificent panorama on the river, the Gellert Hill and the Royal Castle District, a part of the UNESCO World Heritage. The maximum distance between the hotels is 300 meters (0.2 miles), which is an easy 5 minute walk.

IEEE INTERNATIONAL CONFERENCE ON COMMUNICATIONS

Bridging the Broadband Divide
9-13 June • Budapest, Hungary

CALL FOR PAPERS

The 2013 IEEE International Conference on Communications (ICC) will be held in the vibrant city of Budapest, Hungary from 9 – 13 June 2013. This flagship conference of IEEE Communications Society aims at addressing an essential theme on “Bridging the Broadband Divide.” The conference will feature a comprehensive technical program including several Symposia and a number of Tutorials and Workshops. IEEE ICC 2013 will also include an attractive expo program including keynote speakers, various Business, Technology and Industry fora, and vendor exhibits. We invite you to submit your original technical papers, industry forum, workshop, and tutorial proposals to this event. Accepted and presented papers will be published in the IEEE ICC 2013 Conference Proceedings and in IEEE Xplore®. Full details of submission procedures are available at http://www.ieee-icc.org/2013.

To be published in the IEEE ICC 2013 Conference Proceedings and IEEE Xplore®, an author of an accepted paper is required to register for the conference at the full or limited (member or non-member) rate and the paper must be presented at the conference. Non-refundable registration fees must be paid prior to uploading the final IEEE formatted, publication-ready version of the paper. For authors with multiple accepted papers, one full or limited registration is valid for up to 3 papers. Accepted and presented papers will be published in the IEEE ICC 2013 Conference Proceedings and IEEE Xplore®.

PLANNED TECHNICAL SYMPOSIA

Selected Areas in Communications Symposium
E-Health Area
Pradeep Ray, University of New South Wales, Australia
Healthcare Communications Area
Andrea Tomello, University of Udine, Italy
Stephan Willems, University of Strathclyde, UK
Smart Grids Area
Bahram Hannay, Lancaster University, UK
Tactical Communications & Operations Area
Gabe Jakobsen, Attusys, USA
Satellite & Space Communication Area
Hiromitsu Wakana, NICT, Japan
Data Storage Area
Tifany Jing Li, Lehigh University, USA
Access Systems and Networks Area
Michael Peeters, Alcatel-Lucent, Belgium
Green Communication Systems and Networks
Athanasios Menkas, Imperial College London, UK
Wireless Communications Symposium
Zhaochong Wang, Tsinghua University, China
Metra B. Mobesh, Indian Institute of Science, India
Hanna Bogdanska, Poznan University of Technology, Poland
Fredrik Tufvesson, Lund University, Sweden
Wireless Networking Symposium
Azzedine Boukerche, University of Ottawa, Canada
Pan Li, Mississippi State University, USA
Min Chen, Seoul National University, Korea
Communication Theory Symposium
David Gesbert, EUROCOM, France
Angela Lozano, Universitat Pompeu Fabra, Spain
Valio Traji, University of Ferrara, Italy
Semmra Uluisk, University of Maryland, USA
Signal Processing for Communications Symposium
Hsi Lin, Osaka Prefecture University, Japan
Octavia Dobre, Memorial University, Canada
Sadid Boussakta, Newcastle University, UK
Hongyang Chen, Fujitsu Laboratories, Japan
Optical Networks and Systems Symposium
Xavier Masip-Bruin, Technical University of Catalonia, Spain
 Franco Calligati, University of Bologna, Italy
Tibor Cinkler, Budapest University of Technology and Economics, Hungary
Next-Generation Networking Symposium
Malathi “MV” Vedaranganathan, University of Virginia, USA
Joel Rodrigues, University of Beira Interior, Portugal
Wojciech Kaczmarski, Poznan University of Technology, Poland
Communication QoS, Reliability & Modeling Symposium
Tetsuya Yokota, Mitsubishi Electric Corporation, Japan
Harry Skianis, University of the Aegean, Greece
Jens Tapodiac, Budapest University of Technology and Economics, Hungary
Ad-hoc and Sensor Networking Symposium
Guoliang Xue, Arizona State University, USA
Abdallah Shami, University of Western Ontario, Canada
Xinbing Wang, Shanghai Jiaotong University, China
Communication Software and Services Symposium
Jiangtao (Gene) Wei, Tsinghua University, China
Lynda Mokdad, University Paris-Est, France
Communication and Information Systems Security Symposium
Tania Alipan, TU Berlin, Germany
Mark Filippakopoulos, Budapest University of Technology and Economics, Hungary
Keje Lu, University of Puerto Rico at Mayaguez, PR
Cognitive Radio and Networks Symposium
Honggang Zhang, Zhejiang University, China
David Grace, University of York, UK
Andrea Giorgetti, University of Bologna, Italy

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CEO, Magyar Telekom, Hungary

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University of Southampton, UK

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Workshops Co-Chairs:
Thomas Michael Bolmer,
Zurich University of Applied Sciences, Switzerland

Workshop Co-Chairs:
Christoph Miecklenbrucker,
Venice University of Technology, Austria

Panel Session Co-Chairs:
David Soldani,
Haweei, Germany

Publications Co-Chairs:
Dong In Kim,
Seoul National University, Korea

Publications Chair:
John Vtg,
IEEE, USA

IEEE ICC 2013, 9-13 June, Budapest, Hungary

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Germany

GITC Advisor:
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University of Edinburgh, UK

ComSoc Project Manager:
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IEEE ComSoc, USA

Local Arrangements Chair:
Nandor Matrai
Association, Hungary

Finance Chair:
Peter Nagy,
HTE, Hungary

Treasurer:
Bruce Worthman
IEEE ComSoc, USA

IMPORANT DATES

Paper Submission
16 September 2012

Acceptance Notification
27 January 2013

Camera-Ready Manuscripts
24 February 2013

Tutorial Proposal
7 October 2012

Workshop Proposal
28 June 2012

Business Forum Proposal
8 April 2012

Patronage Brochure
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http://www.ieee-icc.org/2013
e-mail: icc2013@hte.hu

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e-mail: vida@tmit.bme.hu

Patronage Chair
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Ericsson Hungary
e-mail: roland.jakab@ericsson.com